

IN THE CLAIMS:

Please amend the claims as follows:

1. **(Currently Amended)** An electrostatic chucking device having a laminated structure which is formed by sequentially laminating a first insulation layer, an electrode layer and a second insulation layer on an aluminum alloy metal substrate, wherein the first insulation layer and the second insulation layer are constituted of polyimide films, and ~~at least an~~ adhesive layer between the aluminum alloy metal substrate and the first insulation layer ~~is achieved by using~~ wherein the adhesive layer includes a diamino siloxane-modified thermoplastic polyimide-based adhesive film having a film thickness of 5 to 50 μm and ~~having a softening point at a~~ compression bonding temperature of 100 to 200°C.

2. **(Currently Amended)** An electrostatic chucking device according to claim 1, wherein the ~~adhesion~~ adhesive layer between the aluminum alloy metal substrate and the first insulation layer, an ~~adhesion~~ adhesive layer between the first insulation layer and the electrode layer and an ~~adhesion~~ adhesive layer between the electrode layer and the second insulation layer each includes the ~~are respectively performed by using~~ diamino siloxane-modified thermoplastic polyimide-based adhesive film ~~[[films]]~~ having ~~[[a]] the~~ film thickness of 5 to 50 μm ~~having a softening point at a temperature of 100 to 200°C and by subjecting the thermoplastic polyimide-based adhesive films to a low temperature and the~~ compression bonding processing under pressure at a temperature of 100 to 200°C.

3-4. **(Canceled).**

5. **(Original)** An electrostatic chucking device according to claim 1, wherein the polyimide films which constitute the first insulation layer and the second insulation layer have a film thickness of 20 to 50 μm .

6. **(Original)** An electrostatic chucking device according to claim 2, wherein the polyimide films which constitute the first insulation layer and the second insulation layer have a film thickness of 20 to 50 μm .

7. **(Withdrawn)** An electrostatic chucking device manufacturing method including

a step in which a thermoplastic polyimide-based adhesive film having a film thickness of 5 to 50 μm , a polyimide film which constitutes a first insulation layer, a thermoplastic polyimide-based adhesive film having a film thickness of 5 to 50 μm , a metal foil which constitutes an electrode layer, a thermoplastic polyimide-based adhesive film having a film thickness of 5 to 50 μm and a polyimide film which constitutes a second insulation layer are sequentially superposed on a metal substrate, and

a step in which a low-temperature compression bonding processing is performed at a heating temperature of 100 to 250°C under pressure so as to form a laminated structure which is constituted by sequentially laminating the first insulation layer, the electrode layer and the second insulation layer on the metal substrate.

8. **(Withdrawn)** An electrostatic chucking device manufacturing method including

a step in which an electrode layer is formed on one-side surface of a first insulation layer or a second insulation layer by means of vapor deposition means or

plating means,

a step in which a thermoplastic polyimide-based adhesive film having a film thickness of 5 to 50 μm , a polyimide film which constitutes the first insulation layer, and

a polyimide film which constitutes the second insulation layer are sequentially superposed on a metal substrate while putting a thermoplastic polyimide-based adhesive film having a film thickness of 5 to 50 μm between the polyimide film which constitutes the first insulation layer or the second insulation layer and the electrode layer, and

a step in which a low-temperature compression bonding processing is performed at a heating temperature of 100 to 250°C under pressure so as to form a laminated structure which is constituted by sequentially laminating the first insulation layer, the electrode layer and the second insulation layer on the metal substrate.

9. **(Withdrawn)** An electrostatic chucking device manufacturing method including

a step in which a polyimide film which constitutes a first insulation layer, a thermoplastic polyimide-based adhesive film having a film thickness of 5 to 50 μm , a metal foil which constitutes an electrode layer, a thermoplastic polyimide-based adhesive film having a film thickness of 5 to 50 μm and a polyimide film which constitutes a second insulation layer are sequentially superposed,

a step in which a low-temperature compression bonding processing is performed at a heating temperature of 100 to 250°C under pressure so as to form an electrostatic chucking sheet which is constituted by sequentially laminating the first insulation layer, the electrode layer and the second insulation layer,

a step in which the electrostatic chucking sheet is superposed on a metal substrate by way of a thermoplastic polyimide-based adhesive film having a film thickness of 5 to 50 μm , and

a step in which a low-temperature compression bonding processing is performed at a heating temperature of 100 to 250°C under pressure so as to form a laminated structure which is constituted by sequentially laminating the first insulation layer, the electrode layer and the second insulation layer on the metal substrate.

10-11. **(Canceled).**

12. **(Withdrawn)** An electrostatic chucking device manufacturing method according to claim 7, wherein at least one of the thermoplastic polyimide-based adhesive films is a siloxane modified thermoplastic polyimide-based adhesive film.

13. **(Withdrawn)** An electrostatic chucking device manufacturing method according to claim 7, wherein each of the thermoplastic polyimide-based adhesive films is a siloxane modified thermoplastic polyimide-based adhesive film.

14. **(Withdrawn)** An electrostatic chucking device manufacturing method according to claim 8, wherein at least one thermoplastic polyimide-based adhesive film is a siloxane modified thermoplastic polyimide-based adhesive film.

15. **(Withdrawn)** An electrostatic chucking device manufacturing method according to claim 8, wherein both thermoplastic polyimide-based adhesive films are siloxane modified thermoplastic polyimide-based adhesive films.

16. **(Withdrawn)** An electrostatic chucking device manufacturing method according to claim 7, wherein the thermoplastic polyimide-based adhesive films have a film thickness of 20 μm to 50 μm .

17. **(Withdrawn)** An electrostatic chucking device manufacturing method according to claim 8, wherein the thermoplastic polyimide-based adhesive films have a film thickness of 20 μm to 50 μm .

18-19. **(Cancelled)**.